Lead-free Wave Soldering Machine

Models: PEAK series



Machine Schematic



Peak Series Main Features



Flux Spraying system

- Modularize Flux Spraying system
 - Plug in and remove connector easily
 - Drawer type structure that easy to install or disassemble to maintain
 - Air filter easy to remove for cleaning







www.suneast.com.cn

Flux Spraying system

(Patent number in China: 201020220532.3)

- Flux spraying is perpendicular to the PCB
 - Spread more even on PCB
 - Enhance flux penetrating property to the holes
 - Improve the adhesiveness of the solder metal
 - Effectively reduce the customer's operating cost
- Software will optimize the path to guarantee the flux coating uniformity







www.suneast.com.cn

Flux Spraying system (option 1)

(Ultrasonic nozzles)

- Ultrasonic nozzles systems reduce: ۰
 - Flux consumption
 - Wasteful overspray and wasteful contamination
 - Waste disposal
 - Servicing and downtime
- Flux spraying <u>cannot</u> be perpendicular to the PCB • because of nozzle design



Flow meter



Conventional nozzle



Ultrasonic nozzle





Flux Spraying system (option 2)

(Selective Spraying)

- Suggest applying to the product which the spraying area is less than 50%
- Flux spraying could be a spot, line or rectangle (Use Japanese Fuso Seiki nozzle HM- $3\varphi 1$) by nozzle motion
- Nozzle is controlled by motor for partial selective flux spraying
- Flux spraying <u>cannot</u> be perpendicular to the PCB because of nozzle design
- The flux spraying module cannot be removed







www.suneast.com.cn

Flux Spraying system (option 2)

(Selective Spraying)

• Flux spraying area VS the percentage of reduced flux

% of reduced flux	Flux spraying area	% of reduced flux
78.20%		84.08%
Ф.А.В.ВИ Ф.А.В.ВИ Ф.А.В.И ВИН: 25446.85 3547.14 ВИН: 21.80% ВИН: 78.20%		Алджан 26002.36 Алджан 4138.58 Вни 15.92% Вни 54.05%
68.13%	60	42.39%
Ф.А.Шант 20894.02 Ф.Аджавет 6659.77 Веть 31.87% Ветьстичник 68.13%		
	78.20%	78.20% ************************************

www.suneast.com.cn

Preheating system

- Modularize Flux Spraying system
 - Plug in and remove connector easily
 - Drawer type structure that easy to install or disassemble to maintain
 - Easy from hot air to IR





Preheating system

• All hot air modules are for better temperature uniformity

• All IR modules are increasing the temperature in a short time



• When Hot air mixed with IR (flexible combination), the temperature can be ramping up in a short time and also good in temperature uniformity. It is suitable for water soluble flux

For standard, only lower part have heating modules and upper part is an option



Soldering pot

- Modularize solder pot
 - Plug in and remove power source and thermocouple easily
 - Standard solder pot, suitable different models and PCB size
 - Peak series auto in/out & up/down





Soldering pot – design characteristics

- 10mm thickness casting iron solder pot
 - No easy to deform when heating
 - Well contact with heater for more uniform heating
- Used graphite for insolation
 - anti-moisture and anti-corrosion
- Ceramic coating
 - smoother surface, anti-corrosion, longer lifetime
- Insolation and large solder pot
 - reduces heat loss
 - make the solder temperature to be more uniform
 - improves the solder pot heat storage capability.





Soldering pot – Warranty

Long lifetime and good temperature uniformity solder pot by casting iron solder with ceramic coating





	Solder Pot Size (mm)	Solder Pot Thickness (mm)	Service life (year) 8 hour / day
316 stainless steel	1150 × 480 × 26 5	3	≥1
Titanium		2	≥5
Heat-resistant casting iron		10	≥8

*Titanium solder pot guaranteed for 2 years

Soldering pot – anti-oxidation

- In 2007, Invited Harbin Institute of Technology researched the factors of oxidation during wave soldering process.
 - Contact area, wave velocity, soldering temperature and wave exposed level
- Reviewed the design by above factors. Solder residue is limited < 0.4kg per hour. Cost saved by better utilization.

Dynamic rotating cap isolate air and limit the oxidation



Cap should be clean at least a week

The oxidation reducing cover effectively control the wave flowing speed, lower the falling height and eliminate oxide.



Solder residue should be removed everyday

Soldering pot – Oxidation residue report

- Testing Criteria
 - Simulate normal plate production process
 - Solder pot temperature : 250 degree
 - Peak width : 400mm
 - Wave height : 8mm
 - Testing time : 8 hours





国内		国外			
机型		日东	国内某品牌	美国 著名品牌	德国 著名品牌
波峰宽度(mm)		400	400	600	500
成渣量 kg/8h		<2	4	8	8

Soldering pot – Wave generation

(Patent number in China: ZL201020220271.5 & ZL200720121628.2)

- The structure of channel and impeller directly influence the soldering wave stability
- The variation of wave level can be controlled within 0.5mm to ensure good welding.

Impeller design

• The impeller design can convert the energy to solder pot constantly for forming more stable solder wave

Channel design

- The channel design optimize the interference between solder wave (more stable)
- Rectifier make the peak of wave more flat



Soldering pot – Nitrogen control

(Patent number in China: 201220052902.6)

- Partial nitrogen charging device for solder pot
- Stainless steel porous pipe sprays nitrogen evenly and stably
- Nitrogen will be blocked below the PCB and from a low oxygen layer between the PCB and the solder pot surface in order to achieve high welding quality and low oxidation.
- Since it is not closed area, oxygen analyzer cannot be installed

1000ppm, 12m3/h Test at soldering level

Pressure: 5bar Flow rate : >18m3/h



Soldering pot – Nitrogen control

(Patent number in China: 201220052902.6)

- Field feedback for wave soldering with N2
 - Short-circuit and incomplete weld are reduced.
 - PCB surface is clean and smooth, without oxidation, and few solid residues.
 - The welding spot is bright, clean, without oxidation and few flux residues.
 - The flux residues is largely reduced, compared with welding under air and the PCB has little adhesion.
 - In addition, the welding spot strength will be enhanced in principle, reducing return to factory repair and the machine using life will be prolonged.

Wave soldering without N2

incomplete welding



Wave soldering with N2



Soldering pot – Performance improved by Nitrogen control

• Yield improvement



• Reducing solder dross amount by nitrogen

Solder dross amount	Solder dross amount	Solder dross
(without nitrogen)	(with nitrogen)	reduced %
0.4kg/h	0.027kg/h	93.30%

Cooling system

• Air cooling from up and down





Clamping



▲ 轻型双钩爪

	Item	参数(Parameter)	Сс
	Technical distance	≥3mm	ve
1.4	PCB thichness	≤2.5mm	ho
88	Carrying ability parameter : the whole conveyor	≪130kg	
轻型双钩爪 Light-duty double Hook Finger	Material	材料有不锈钢和钛合金两种 Material is stainless steel and titan- nium alloy	
T			

ost down ersion for double ook finger

Type 1 finger : Stainless steel Type 2 finger : Titanium

Item	参数(Parameter)
Technical distance	≥2mm
PCB thichness	≪3.5mm
Carrying ability parameter : the whole conveyor	≪130kg
Material	钛合金材料 Titanium alloy

Current standard

▲ 重型双钩爪 Double hook finger

Type 3 finger : Titanium

Clamping



▲ 重型弹簧压片爪 Spring pressed finger

Type 4 finger

▲ D-40鸭嘴爪 D-40 duchbill finger



Item	参数(Parameter)
Technical distance	≥4mm
PCB thichness	≪5mm
Carrying ability parameter : the whole conveyor	≪130kg
Material	支撑片钛合金材料,压片不锈钢材料 support chip is titanium alloy, tabletting is stainless steel

Item	参数(Parameter)
Technical distance	≥3mm
PCB thichness	≪2mm
Carrying ability parameter : the whole conveyor	≪130kg
Material	钛合金材料 Titanium alloy

Cleaning

 Alcohol will to pump to the brush and clean the clamp during moving





Other feature – User friendly interface



Direct input target temperature into the program Display actual temperature

Other feature – Digitization interface



Machine qualification

Use ESAMBER tester to check the thermal performance

- Temperature profile
- Temperature accuracy
- Temperature repeatability of different heating zones



Wave Soldering Machine

Specification

型号 Model NO	PEAK-350	PEAK-450	PEAK-610
外形尺寸 Dimension: L×W×H(mm)	4450×1400×1700	4450×1500×1700	4450×1670×1700
重量 Weight	Approx.1800kg	Approx.2100kg	Approx.2600kg
电源 Power Supply	3PH 380V 50HZ	3PH 380V 50HZ	3PH 380V 50HZ
启动功率 Startup Power	32KW	32KW	45KW
正常运行功率 Operation Power Consumption	Approx.8KW	Approx.8KW	Approx.11KW
控制系统 Control System	PC+PLC	PC+PLC	PC+PLC
喷雾移动 Spraying movement	步进马达(Step motor)	步进马达(Step motor)	步进马达(Step motor)
喷雾气压 Spray Pressure	0.2Mpa~0.4Mpa	0.2Mpa~0.4Mpa	0.2Mpa~0.4Mpa
助焊剂流量控制 Flux Flow Arrange	Option	Option	Option
助焊剂自动添加 Auto Fill Flux	标配(Standards)	标配(Standards)	标配(Standards)
抽风方式 Exhaust	上抽风(Top exhaust)+侧抽风(Side exhaust)	上抽风(Top exhaust)+侧抽风(Side exhaust)	上抽风(Top exhaust)+侧抽风(Side exhaust)
抽风管直径 Exhaust Ducting Diameter (mm)	Ø250	Ø250	Ø250
排风量 Exhaust Capacity	30M³/min	30M³/min	30M³/min
预热方式 Preheating Mode	微热风/红外(Convection/IR emitter)	微热风/红外(Convection/IR emitter)	微热风/红外(Convection/IR emitter)
温度控制方式 Control Mode	PID	PID	PID
预热区数量 Preheating Zone Number	3	3	3
预热区长度 Preheating Length (mm)	1800	1800	1800
预热温度可调范围 Preheating Temperature	室温(Room temperature)~200℃	室温(Room temperature)~200℃	室温(Room temperature)~200℃
预热升温时间 Warm-up Time(min)	Approx.12min(setting:150°C)	Approx.12min(setting:150°C)	Approx.12min(setting:150°C)
热风马达 Blower Motor	250W 3PH 220 VAC	250W 3PH 220 VAC	250W 3PH 220 VAC
宽度范围 PCB Width(mm)	50~350	50~450	50~610

Wave Soldering Machine

Specification

型号 Model NO	PEAK-350	PEAK-450	PEAK-610	
PCB传送方向 Conveyor Direction	$L \rightarrow R(Option: R \rightarrow L)$	L→R(Option:R→L)	$L \rightarrow R(Option: R \rightarrow L)$	
传送速度范围 Conveyor Speed(mm/min)	500~1800	500~1800	500~1800	
运输高度 Conveyor Height(mm)	750±20	750±20	750±20	
允许PCB元件高度 Available Component Height(mm)	上(Top)120(Option:250)下(Bottom)15	上(Top)120(Option:250)下(Bottom)15	上(Top)120(Option:250)下(Bottom)15	
速度控制方式 Conveyor Speed Control Mode	变频器闭环无级调速(Closed loop)	变频器闭环无级调速(Closed loop)	变频器闭环无级调速(Closed loop)	
爪 Fingers	新型双钩爪(New Design Double-hook Ty Finger): ②D-40型鸭嘴爪(D-40 Type Fir	新型双钩爪(New Design Double-hook Type) Option:治具专用爪		
导轨角度 Conveyor Angle	4~7°	4~7°	4~7°	
锡炉类型 Type of solder Pot	机械式(Motor drive)	机械式(Motor drive)	机械式(Motor drive)	
锡炉材质 Solder Pot Material	铸铁(Casting Iron)	铸铁(Casting Iron)	全钛(Full titanium)	
波峰调节方式 Wave Height Adjustment	变频器(Inverter) Approx: 电脑数字控制(Digital Control by PC)			
冷却方式 Cooling Method	强制风冷(Air Cooling) Option: 冷水机(Water cooling)			
锡炉加热功率 Heater Power	220V 13.5KW	220V 13.5KW	380 VAC 18KW	
锡炉最高温度 Solder Pot Temperature	300°C	300°C	300°C	
锡炉容量 Solder Pot Capacity	500kg	500kg	650kg	
波峰驱动功率 Wave Drive Power	180W×2 3PH 220 VAC	180W×2 3PH 220 VAC	180W×2 3PH 220 VAC	
锡炉升温时间 Solder Pot Warm-up Time	Approx.150min(setting: 250°C)	Approx.150min(setting: 250°C)	Approx.150min(setting: 250°C)	
炉温控制方式 Temperature Control Mode	PID	PID	PID	
洗爪系统 Finger Cleaning System	毛刷(Brush)	毛刷(Brush)	毛刷(Brush)	

Option

Wave Soldering Machine

- The material of Peak series will be higher class
- The price of NSI will be more competitive

	Peak series	NSI series
PLC control	Siemens	China brand
PC	Industrial PC	Commercial PC from China
Cover	Streamline design and stronger	Standard
CE Certification	Yes	No
Flow channel & nozzle	Titanium	Stainless steel
Finger	Titanium double hook (Type III)	Stainless steel Light-duty double hook (Type I)
Auto up/down/in/out of solder pot	Yes	No

THANKS!